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Electronic Components Sourcing Information

Product Reference Information

Part Number:	BUK6Y19-30PX
Manufacturer:	Nexperia USA Inc.
Package:	Please confirm with sales
Availability:	Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nexperia-usa-inc/buk6y19-30px.html>

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Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.



BUK6Y19-30P

30 V, P-channel Trench MOSFET

13 March 2026

Product data sheet

1. General description

P-channel enhancement mode MOSFET in an LFPAK56 (Power SO8) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

This product has been designed and qualified to AEC-Q101 standard for use in high-performance automotive applications such as reverse battery protection.

2. Features and benefits

- High thermal power dissipation capability
- Suitable for thermally demanding environments due to 175 °C rating
- Trench MOSFET technology
- AEC-Q101 qualified

3. Applications

- Reverse battery protection
- Power management
- High-side load switch
- Motor drive

4. Quick reference data

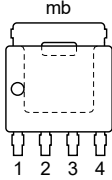
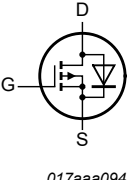
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$		-	-	-30	V
V_{GS}	gate-source voltage		[1]	-20	-	20	V
I_D	drain current	$V_{GS} = -10\text{ V}; T_{mb} = 25\text{ °C}$		-	-	-45	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$		-	-	66	W
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10\text{ V}; I_D = -9.5\text{ A}; T_j = 25\text{ °C}$		-	15	19	mΩ

[1] $V_{GS} = -20\text{ V}/+5\text{ V}$ according AEC-Q101 at $T_j = 175\text{ °C}$; $V_{GS} = -20\text{ V}/+20\text{ V}$ according AEC-Q101 at $T_j = 150\text{ °C}$

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 LFPAK56; Power-SO8 (SOT669)	 <i>017aaa094</i>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK6Y19-30P	LFPAK56; Power-SO8	plastic, single-ended surface-mounted package; 4 terminals	SOT669

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK6Y19-30P	6Y1930P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	-30	V
V_{GS}	gate-source voltage		[1]	-20	20	V
I_D	drain current	$V_{GS} = -10\text{ V}; T_{mb} = 25\text{ }^{\circ}\text{C}$		-	-45	A
		$V_{GS} = -10\text{ V}; T_{mb} = 100\text{ }^{\circ}\text{C}$		-	-32	A
I_{DM}	peak drain current	single pulse; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^{\circ}\text{C}$		-	-181	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ }^{\circ}\text{C}$		-	66	W
T_j	junction temperature			-55	175	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	175	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	175	$^{\circ}\text{C}$
Source-drain diode						
I_S	source current	$T_{mb} = 25\text{ }^{\circ}\text{C}$		-	-45	A
I_{SM}	peak source current	single pulse; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^{\circ}\text{C}$		-	-181	A
ESD maximum rating						
V_{ESD}	electrostatic discharge voltage	HBM	[2]	-	500	V
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{sup} \leq -30\text{ V}; V_{GS} = -10\text{ V}; T_{j(init)} = 25\text{ }^{\circ}\text{C}; R_{GS} = 50\text{ }\Omega; I_D = -28.8\text{ A}; \text{unclamped}$	[3]	-	72.4	mJ
		$V_{sup} \leq -30\text{ V}; V_{GS} = -10\text{ V}; T_{j(init)} = 25\text{ }^{\circ}\text{C}; R_{GS} = 50\text{ }\Omega; I_D = -7.3\text{ A}$	[3]	-	294	mJ
I_{AS}	non-repetitive avalanche current	$T_{j(init)} = 25\text{ }^{\circ}\text{C}$	[3]	-	-28.8	A

[1] $V_{GS} = -20\text{ V}/+5\text{ V}$ according AEC-Q101 at $T_j = 175\text{ }^{\circ}\text{C}$; $V_{GS} = -20\text{ V}/+20\text{ V}$ according AEC-Q101 at $T_j = 150\text{ }^{\circ}\text{C}$

[2] Measured between all pins.

[3] Protected by 100% test

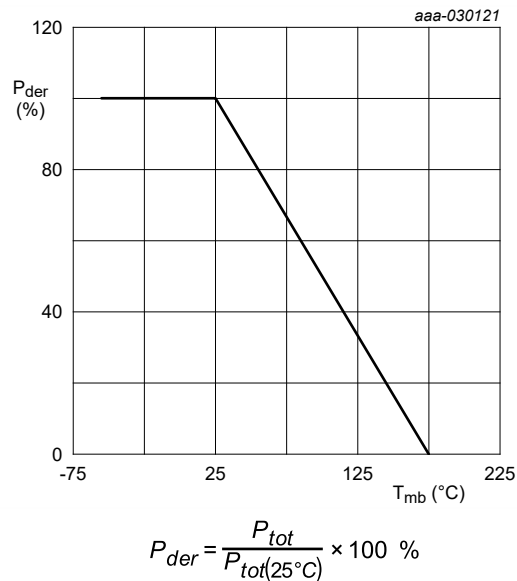


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

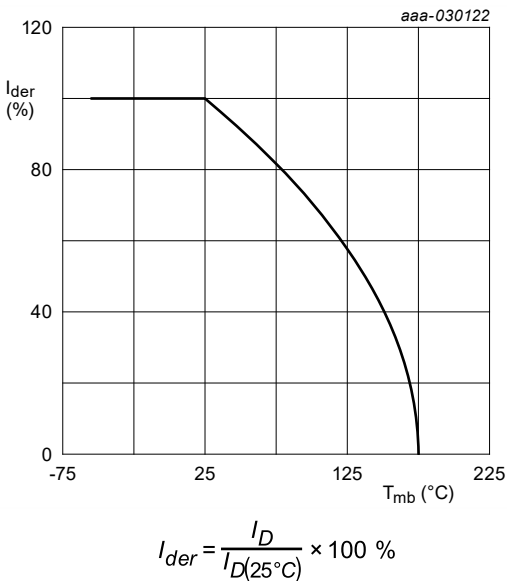


Fig. 2. Normalized continuous drain current as a function of mounting base temperature

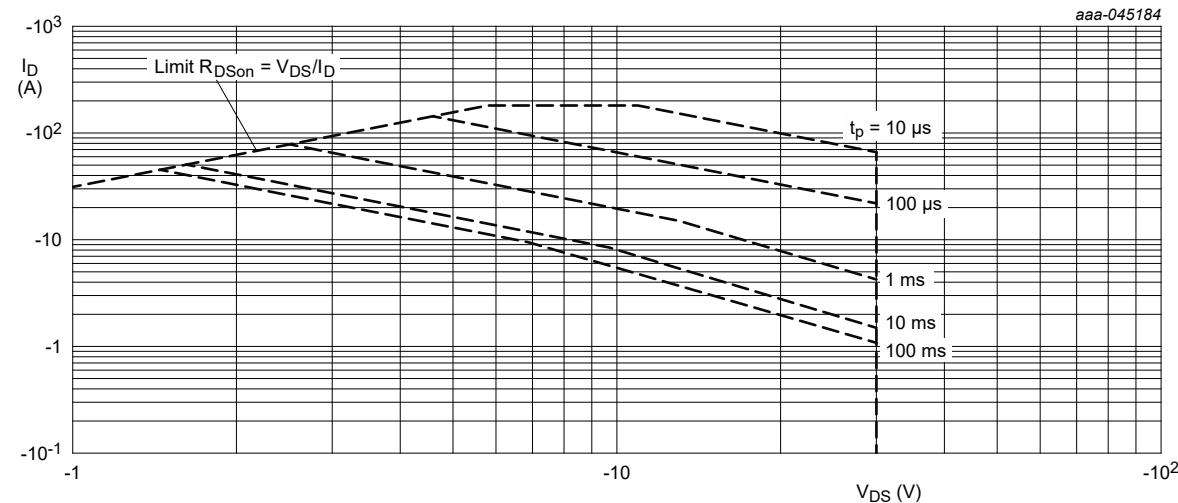


Fig. 3. Safe operating area; junction to mounting base; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base			-	1.8	2.3	K/W

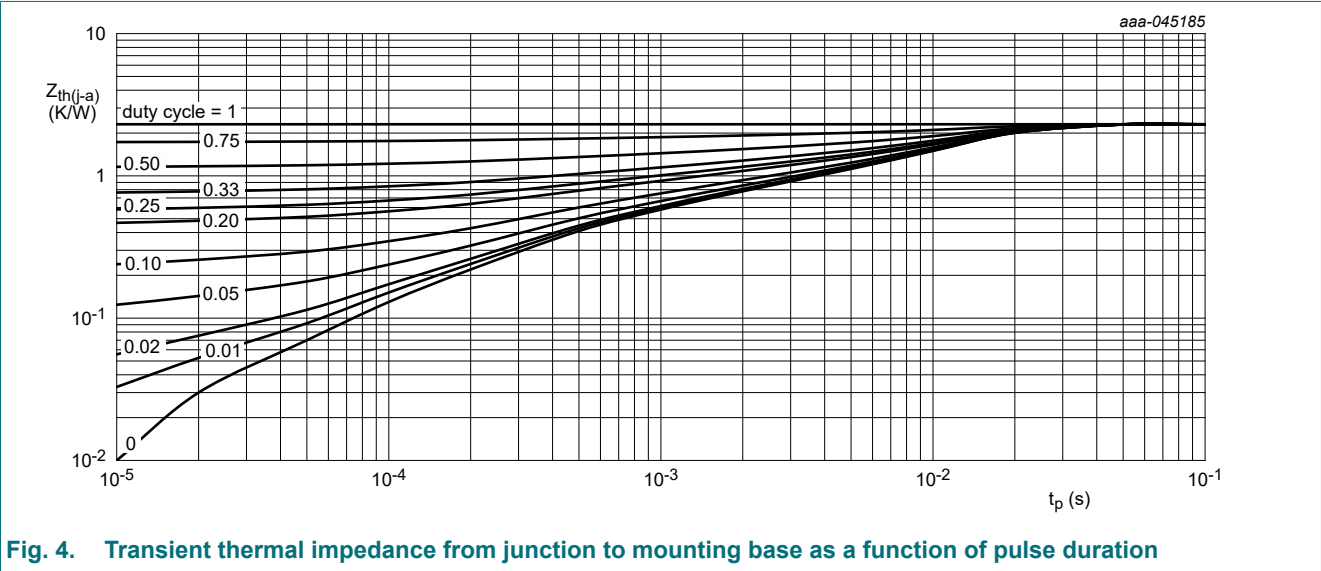


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _{(BR)DSS}	drain-source breakdown voltage	I _D = -250 μA; V _{GS} = 0 V; T _j = 25 °C		-30	-	-	V
V _{GSth}	gate-source threshold voltage	I _D = -250 μA; V _{DS} =V _{GS} ; T _j = 25 °C		-1.5	-2	-3	V
I _{DSS}	drain leakage current	V _{DS} = -30 V; V _{GS} = 0 V; T _j = 25 °C		-	-	-1	μA
		V _{DS} = -30 V; V _{GS} = 0 V; T _j = 125 °C		-	-	-10	μA
I _{GSS}	gate leakage current	V _{GS} = -20 V; V _{DS} = 0 V; T _j = 25 °C		-	-	-100	nA
		V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C		-	-	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = -10 V; I _D = -9.5 A; T _j = 25 °C		-	15	19	mΩ
		V _{GS} = -10 V; I _D = -9.5 A; T _j = 175 °C		-	26	32	mΩ
		V _{GS} = -4.5 V; I _D = -5.9 A; T _j = 25 °C		-	25	50	mΩ
g _{fs}	forward transconductance	V _{DS} = -5 V; I _D = -9.5 A; T _j = 25 °C		-	24	-	S
R _G	gate resistance	f = 1 MHz		-	11	-	Ω
Dynamic characteristics							
Q _{G(tot)}	total gate charge	V _{DS} = -15 V; I _D = -9.5 A; V _{GS} = -10 V; T _j = 25 °C		-	23	35	nC
Q _{GS}	gate-source charge			-	4	-	nC
Q _{GD}	gate-drain charge			-	5	-	nC
C _{iss}	input capacitance	V _{DS} = -15 V; f = 1 MHz; V _{GS} = 0 V; T _j = 25 °C		-	1260	-	pF
C _{oss}	output capacitance			-	270	-	pF
C _{rss}	reverse transfer capacitance			-	150	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = -15 V; I _D = -9.5 A; V _{GS} = -10 V; R _{G(ext)} = 6 Ω; T _j = 25 °C		-	4	-	ns
t _r	rise time			-	11	-	ns
t _{d(off)}	turn-off delay time			-	41	-	ns
t _f	fall time			-	200	-	ns
Source-drain diode							
V _{SD}	source-drain voltage	I _S = -6 A; V _{GS} = 0 V; T _j = 25 °C		-	-0.8	-1.2	V
t _{rr}	reverse recovery time	I _S = -6 A; dI _S /dt = 100 A/μs; V _{GS} = 0 V; V _{DS} = -15 V; T _j = 25 °C		-	18	-	ns
Q _r	recovered charge			-	10	-	nC

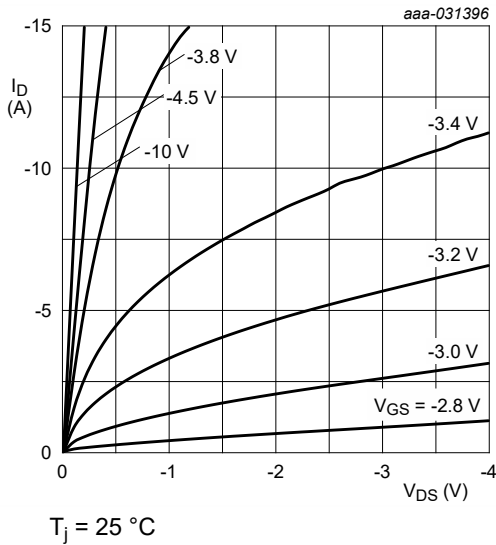


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

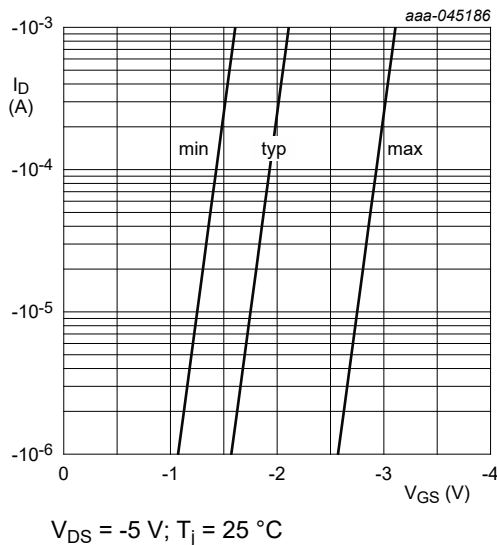


Fig. 6. Sub-threshold drain current as a function of gate-source voltage

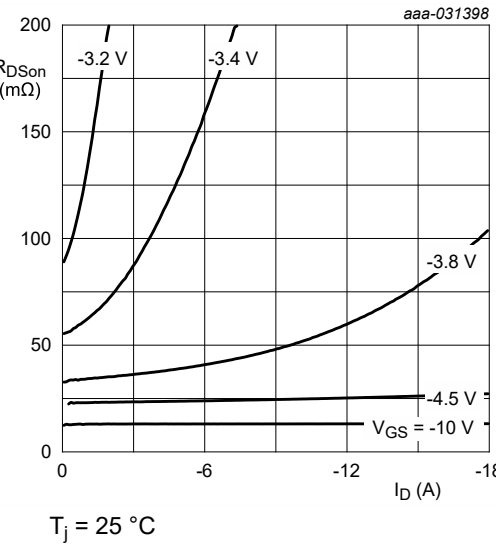


Fig. 7. Drain-source on-state resistance as a function of drain current; typical values

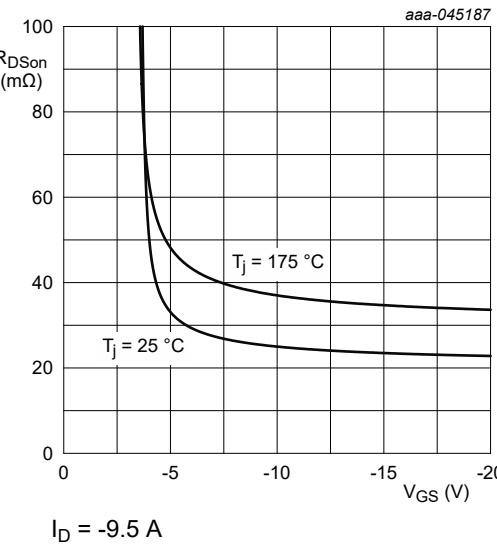


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

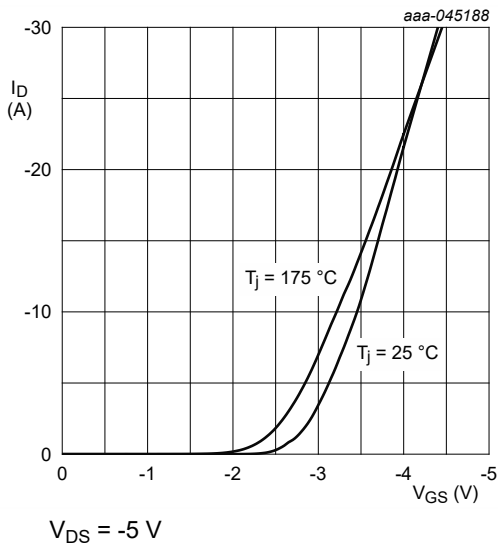


Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

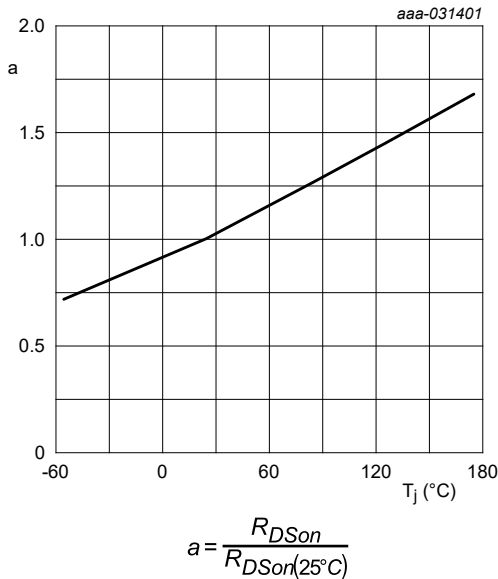


Fig. 10. Normalized drain-source on-state resistance as a function of junction temperature; typical values

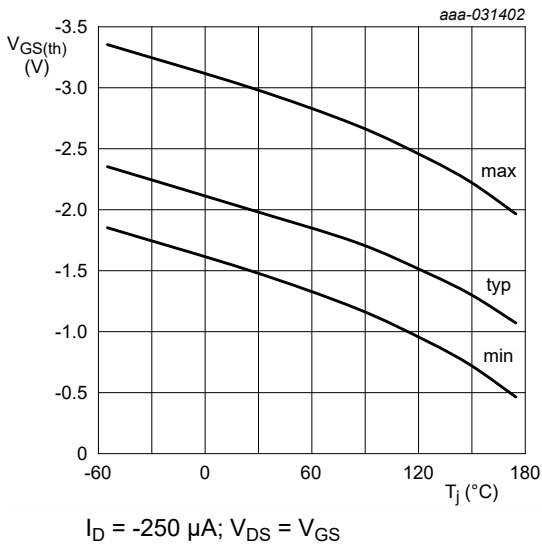


Fig. 11. Gate-source threshold voltage as a function of junction temperature

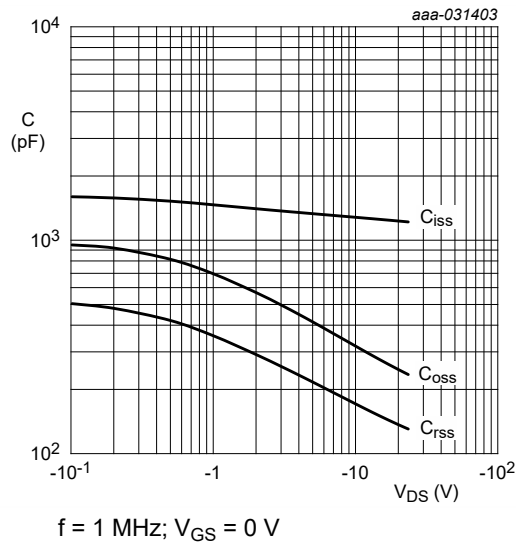


Fig. 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

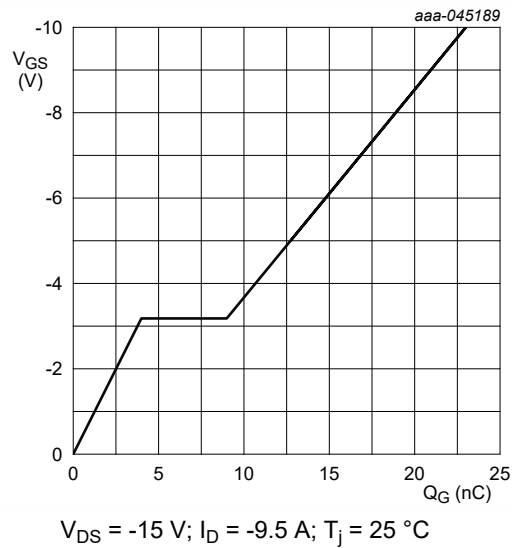


Fig. 13. Gate-source voltage as a function of gate charge; typical values

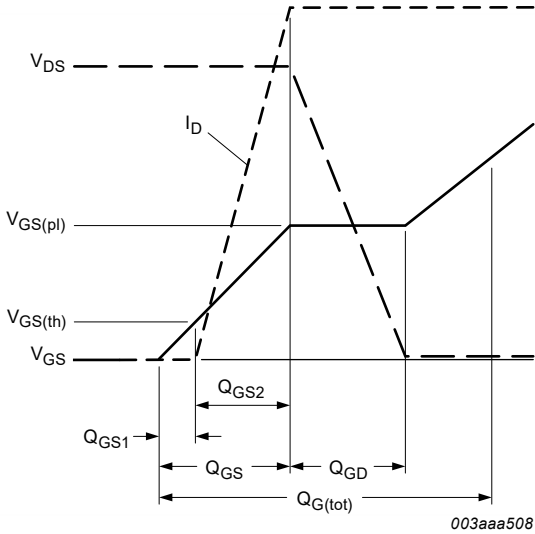


Fig. 14. Gate charge waveform definitions

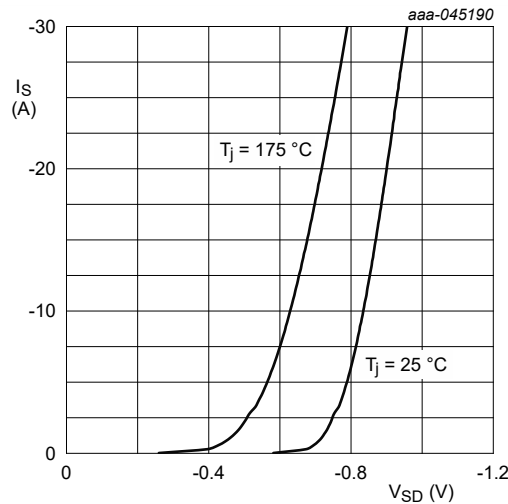


Fig. 15. Source current as a function of source-drain voltage; typical values

11. Test information

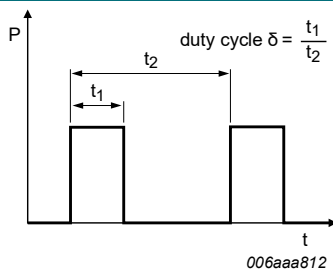


Fig. 16. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

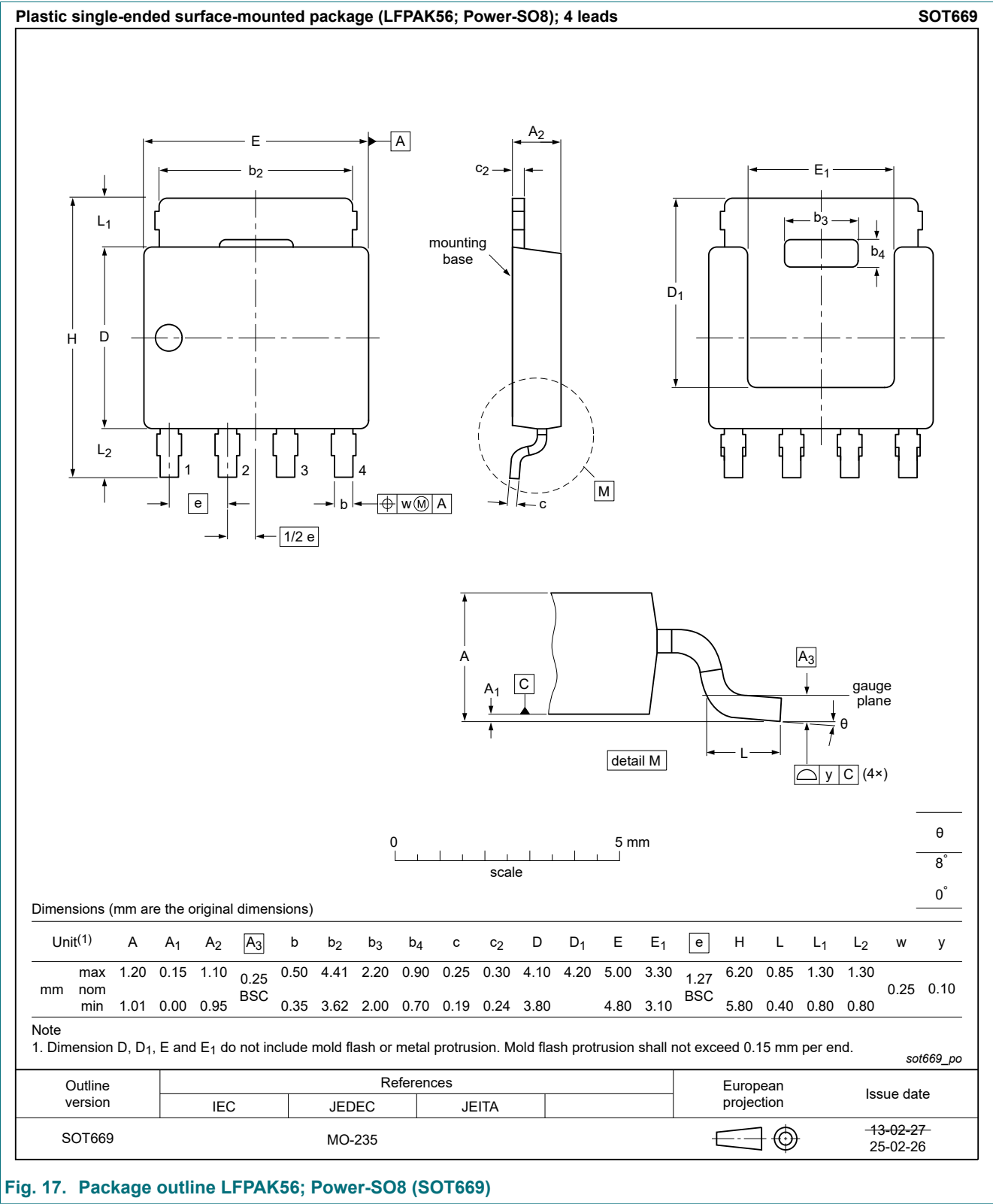


Fig. 17. Package outline LPAK56; Power-SO8 (SOT669)

13. Soldering

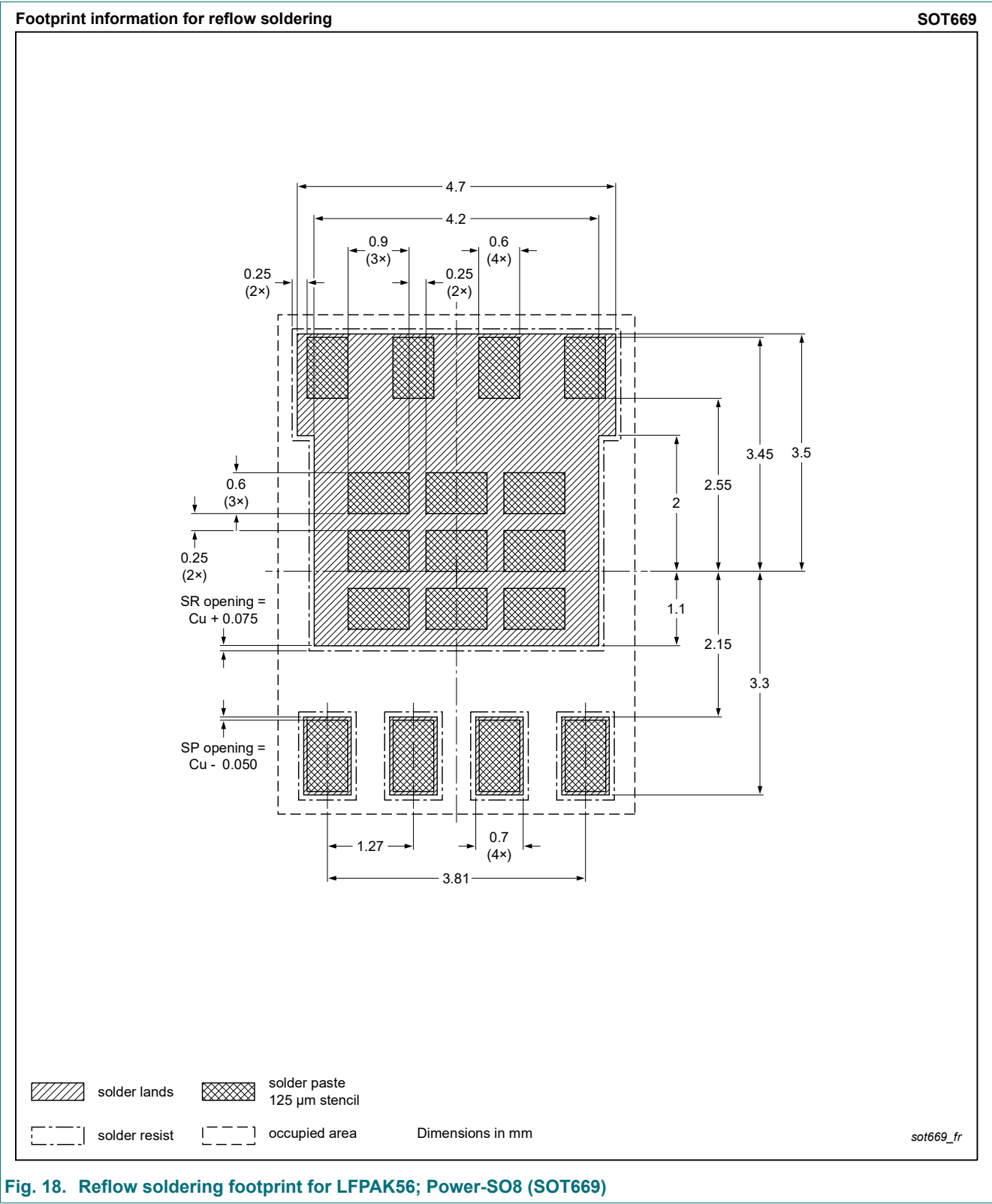


Fig. 18. Reflow soldering footprint for LFPAK56; Power-SO8 (SOT669)

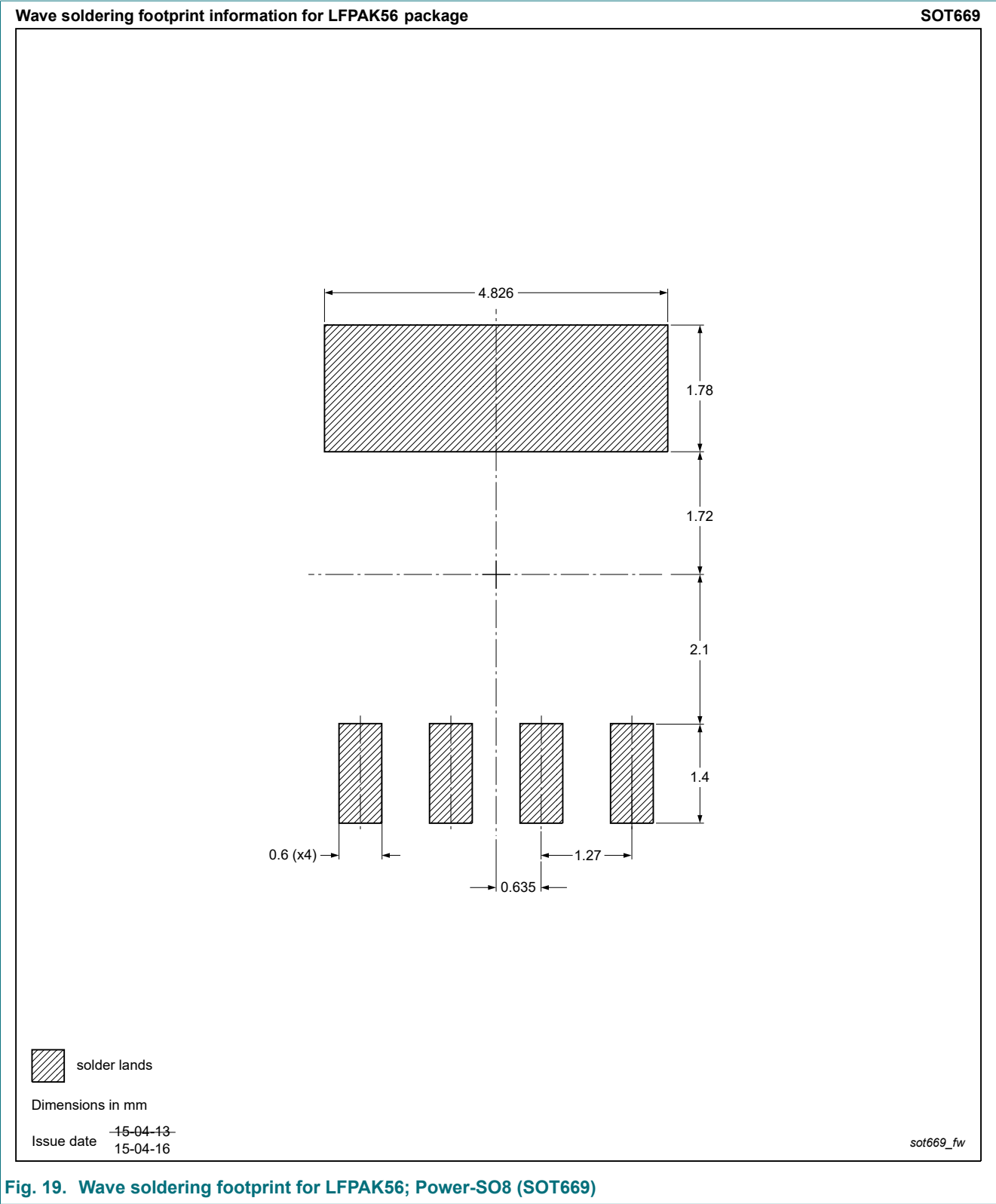


Fig. 19. Wave soldering footprint for LFPAK56; Power-SO8 (SOT669)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BUK6Y19-30P v.2	20260313	Product data sheet	-	BUK6Y19-30P v.1
Modifications:	Complete rework			
BUK6Y19-30P v.1	20200417	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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Contents

1. General description..... 1

2. Features and benefits..... 1

3. Applications..... 1

4. Quick reference data..... 1

5. Pinning information.....2

6. Ordering information.....2

7. Marking.....2

8. Limiting values..... 3

9. Thermal characteristics..... 5

10. Characteristics..... 6

11. Test information..... 10

12. Package outline..... 11

13. Soldering..... 12

14. Revision history..... 14

15. Legal information.....15

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